

FEATURES

- Natural tack
- Good thermal conductivity
- Soft and high compressibility
- Easy to assemble
- Thermal design good insulator
- Shock and vibration absorber

Thermal Interface Sheet, 2.2W/m·K, 150 x 150mm 0.5mm, Self-Adhesive

RS Stock No.: 707-4590



RS Professionally Approved Products bring to you professional quality parts across all product categories. Our product range has been tested by engineers and provides a comparable quality to the leading brands without paying a premium price.



Product Description

RS PRO range of mid performance thermally conductive gap filler which due to their flexible design allows them to fill the air gap between uneven surfaces. Thermal gap pads provide a thermal interface between heatsinks (devices or substances for absorbing unwanted or excess heat) and electronic devices. They're particularly useful where air gaps, rough surface textures or uneven surface topography prevent the use of traditional grease or paste

Options include the following with various thicknesses.

707-4590 - 0.5 mm, 2.2W/mK 707-4594 - 0.8 mm, 2.2W/mK 707-4604 - 1.0 mm, 2.2W/mK 707-4607 - 1.2 mm, 2.2W/mK 707-4601 - 1.5 mm, 2.2W/mK 707-4610 - 2.0 mm, 2.2W/mK 707-4613 - 2.5 mm, 2.2W/mK 707-4617 - 3.0 mm, 2.2W/mK

General Specifications

Material	Silicone
Self-Adhesive	Yes
Colour	Red
Applications	Flat panel displays; LED (light emitting diode) displays; Engine control units; Computer hard drives; Wireless communication hardware
Flame Rating	V0 UL94
Shelf Life	24months

Electrical Specifications

Dielectric Strength	6kV/mm
Dielectric Constant at 1kHz	5
Volume Resistivity	1.38x10 ¹² ohm.cm
Insulation Strength	>5kV/mm



Mechanical Specifications

Dimensions	150x150mm
Thickness	0.5mm
Length	150mm
Width	150mm
Diameter	75mm
Thermal Conductivity	2.2W/(m.K)
Hardness	Shore A 10
Thermal Impedance	<0.28°C-in ² /W
Specific Gravity	2.43g/cm ³
Weight Loss	<1%
Elongation	282%
Tensile Strength	7Kgf/cm ²
Density	3.3g/cm ³
Deflection At 10 psi	3%
Young's Modulus	24N/cm ²
Compression Ratio at 1mm, 40psi	40%
Thermal Resistance	0.8W/m.K
Coefficient Of Thermal Expansion	250ppm/K
Dissipation Factor At 1000kHz	0.013

Operation Environment Specifications Minimum Operating Temperature -40°C Maximum Operating Temperature 200°C

Approvals	
Compliance/Certifications	CE / UR / cUR

Thermal Pads



